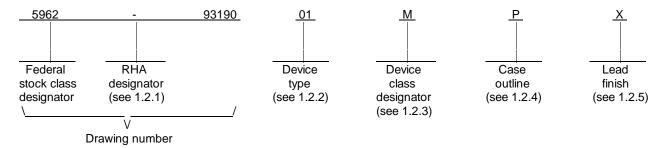
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AMSC	N/A			REV	ISION	LEVEL					4	6	726	8		59	0 2-	931	90	
										SHE	ET	1		OF	13	3				

1. SCOPE

- 1.1 <u>Scope</u>. This drawing forms a part of a one part one part number documentation system (see 6.6 herein). Two product assurance classes consisting of military high reliability (device classes Q, and M) and space application (device class V), and a choice of case outlines and lead finishes are available and are reflected in the Part or Identifying Number (PIN). Device class M microcircuits represent non-JAN class B microcircuits in accordance with 1.2.1 of MIL-STD-883, "Provisions for the use of MIL-STD-883 in conjunction with compliant non-JAN devices". When available, a choice of radiation hardness assurance (RHA) levels are reflected in the PIN.
 - 1.2 PIN. The PIN shall be as shown in the following example:



- 1.2.1 RHA designator. Device class M RHA marked devices shall meet the MIL-I-38535 appendix A specified RHA levels and shall be marked with the appropriate RHA designator. Device classes Q and V RHA marked devices shall meet the MIL-I-38535 specified RHA levels and shall be marked with the appropriate RHA designator. A dash (-) indicates a non-RHA device.
 - 1.2.2 <u>Device type(s)</u>. The device type(s) shall identify the circuit function as follows:

Generic number	<u>Circuit function</u>
LT1241	Controlled, pulse width modulator
LT1242	Controlled, pulse width modulator
LT1243	Controlled, pulse width modulator
LT1244	Controlled, pulse width modulator
LT1245	Controlled, pulse width modulator
	LT1241 LT1242 LT1243 LT1244

1.2.3 <u>Device class designator</u>. The device class designator shall be a single letter identifying the product assurance level as follows:

<u>Device class</u>	Device requirements documentation
М	Vendor self-certification to the requirements for non-JAN class B microcircuits in accordance with 1.2.1 of MIL-STD-883
Q or V	Certification and qualification to MIL-I-38535

1.2.4 Case outline(s). The case outline(s) shall be as designated in MIL-STD-1835 and as follows:

Outline letter	Descriptive designator	<u>Terminals</u>	Package style
Р	GDIP1-T8 or CDIP2-T8	8	Dual-in-line

1.2.5 <u>Lead finish</u>. The lead finish shall be as specified in MIL-STD-883 (see 3.1 herein) for class M or MIL-I-38535 for classes Q and V. Finish letter "X" shall not be marked on the microcircuit or its packaging. The "X" designation is for use in specifications when lead finishes A, B, and C are considered acceptable and interchangeable without preference.

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1.3 Absolute maximum ratings. 1/			
Supply voltage (V_{CC}) Output current (I_{OUT} Output energy (capacitor load per cycle) Analog inputs (FB and I_{SENSE} pins) Error amplifier output sink current Power dissipation (P_D) ($T_A \le +25^{\circ}C$) Storage temperature range Lead temperature (soldering, 10 seconds) Thermal resistance, junction-to-ambient (Θ_{JA}) Thermal resistance, junction-to-case (Θ_{JC})	5 μJ 0.3 V to 10 mA 1 W 65° C to +300° C 100° C/W	+150°C	
1.4 Recommended operating conditions.			
Supply voltage (V_{CC})	+15 V 12 V to 2 55°C to		
2. APPLICABLE DOCUMENTS			
2.1 Government specification, standards, bulletin, and handbook standards, bulletin, and handbook of the issue listed in that issue Standards specified in the solicitation, form a part of this drawing to	of the Department	of Defense Index of Specific	
SPECIFICATION			
MILITARY			
MIL-I-38535 - Integrated Circuits, Manufacturing, Ge	neral Specification	for.	
STANDARDS			
MILITARY			
MIL-STD-883 - Test Methods and Procedures for Mi MIL-STD-973 - Configuration Management. MIL-STD-1835 - Microcircuit Case Outlines.	croelectronics.		
BULLETIN			
MILITARY			
MIL-BUL-103 - List of Standardized Military Drawings	s (SMD's).		
HANDBOOK			
MILITARY			
MIL-HDBK-780 - Standardized Military Drawings.			
(Copies of the specification, standards, bulletin, and handbook r functions should be obtained from the contracting activity or as di			pecific acquisition
2.2 <u>Order of precedence</u> . In the event of a conflict between the drawing shall take precedence.	text of this drawing	g and the references cited h	erein, the text of this
 Stresses above the absolute maximum rating may cause maximum levels may degrade performance and affect rel The 1 A rating for output current is based on transient sw 	iability.		operation at the
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3. REQUIREMENTS

- 3.1 <u>Item requirements</u>. The individual item requirements for device class M shall be in accordance with 1.2.1 of MIL-STD-883, "Provisions for the use of MIL-STD-883 in conjunction with compliant non-JAN devices" and as specified herein. The individual item requirements for device classes Q and V shall be in accordance with MIL-I-38535, the device manufacturer's Quality Management (QM) plan, and as specified herein.
- 3.2 <u>Design, construction, and physical dimensions</u>. The design, construction, and physical dimensions shall be as specified in MIL-STD-883 (see 3.1 herein) for device class M and MIL-I-38535 for device classes Q and V and herein.
 - 3.2.1 Case outline(s). The case outline(s) shall be in accordance with 1.2.4 herein.
 - 3.2.2 Terminal connections. The terminal connections shall be as specified on figure 1.
 - 3.2.2 Logic diagrams. The logic diagrams shall be as specified on figure 2.
- 3.3 <u>Electrical performance characteristics and postirradiation parameter limits</u>. Unless otherwise specified herein, the electrical performance characteristics and postirradiation parameter limits are as specified in table I and shall apply over the full ambient operating temperature range.
- 3.4 <u>Electrical test requirements</u>. The electrical test requirements shall be the subgroups specified in table II. The electrical tests for each subgroup are defined in table I.
- 3.5 <u>Marking</u>. The part shall be marked with the PIN listed in 1.2 herein. Marking for device class M shall be in accordance with MIL-STD-883 (see 3.1 herein). In addition, the manufacturer's PIN may also be marked as listed in MIL-BUL-103. Marking for device classes Q and V shall be in accordance with MIL-I-38535.
- 3.5.1 <u>Certification/compliance mark</u>. The compliance mark for device class M shall be a "C" as required in MIL-STD-883 (see 3.1 herein). The certification mark for device classes Q and V shall be a "QML" or "Q" as required in MIL-I-38535.
- 3.6 <u>Certificate of compliance</u>. For device class M, a certificate of compliance shall be required from a manufacturer in order to be listed as an approved source of supply in MIL-BUL-103 (see 6.7.2 herein). For device classes Q and V, a certificate of compliance shall be required from a QML-38535 listed manufacturer in order to supply to the requirements of this drawing (see 6.7.1 herein). The certificate of compliance submitted to DESC-EC prior to listing as an approved source of supply for this drawing shall affirm that the manufacturer's product meets, for device class M, the requirements of MIL-STD-883 (see 3.1 herein), or for device classes Q and V, the requirements of MIL-I-38535 and the requirements herein.
- 3.7 <u>Certificate of conformance</u>. A certificate of conformance as required for device class M in MIL-STD-883 (see 3.1 herein) or for device classes Q and V in MIL-I-38535 shall be provided with each lot of microcircuits delivered to this drawing.
- 3.8 <u>Notification of change for device class M.</u> For device class M, notification to DESC-EC of change of product (see 6.2 herein) involving devices acquired to this drawing is required for any change as defined in MIL-STD-973.
- 3.9 <u>Verification and review for device class M</u>. For device class M, DESC, DESC's agent, and the acquiring activity retain the option to review the manufacturer's facility and applicable required documentation. Offshore documentation shall be made available onshore at the option of the reviewer.
- 3.10 <u>Microcircuit group assignment for device class M.</u> Device class M devices covered by this drawing shall be in microcircuit group number 110 (see MIL-I-38535, appendix A).
 - 4. QUALITY ASSURANCE PROVISIONS
- 4.1 <u>Sampling and inspection</u>. For device class M, sampling and inspection procedures shall be in accordance with MIL-STD-883 (see 3.1 herein). For device classes Q and V, sampling and inspection procedures shall be in accordance with MIL-I-38535 and the device manufacturer's QM plan.

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TABLE I.	Electrical performance characteristics.	
	•	

Test	Symbol	Conditions <u>1</u> / <u>2</u> /	Group A	Device	Limits		Units
		-55° C ≤ T _A ≤ +125° C unless otherwise specified	subgroups	type	Min	Max	
Reference section							
Output voltage	V _{OUT}	I_{OUT} 1 mA, $T_A = +25^{\circ}$ C	1	All	4.925	5.075	V
Line regulation	VR _{LN}	V _{IN} = 12 V, 25 V	1, 2, 3	All		20	mV
Load regulation	VR _{LD}	I _{OUT} = 1 mA, 20 mA	1, 2, 3	All		-25	mV
Total output variation	V _{TOV}	Line, Load, temperature	1, 2, 3	All	4.87	5.13	V
Output short circuit current	los		4, 5, 6	All	-30	-180	mA
Oscillator section							
Initial accuracy	fosc	$R_T = 10 \text{ k}\Omega, \ C_T = 3.3 \text{ nF}, \ T_A = +25^{\circ}\text{C}$	4	All	47.5	52.5	kHz
		$R_T = 13 \text{ k}\Omega, \ C_T = 500 \text{ pF}, \ T_A = +25^{\circ}\text{C}$			228	268	
Voltage stability	fV _{OSC}	V _{CC} 12 V, 25 V, T _A = +25°C	4	All		1	%
Clock ramp reset current	I _{RCLK}	V _{OSC} = 2 V, T _A = +25° C	4	All	7.9	8.5	mA
Error amplifier section							
FEEDBACK (FB) pin input voltage	V _{FIN}	V _{COMP} = 2.5 V	1, 2, 3	All	2.42	2.58	V
Input bias current	I _{IB}	V _{FB} = 2.5 V	1, 2, 3	All		-2	μ A
Open loop voltage gain	A _{VOL}	V _{OUT} = 2 V, 4 V	4, 5, 6	All	65		dB

See footnotes at end of table.

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TABLE I. <u>Electrical performance characteristics</u> - Continued.							
Test	Symbol	Conditions <u>1</u> / <u>2</u> /	Group A	Device	Limits		Units
		-55°C ≤ T _A ≤ +125°C unless otherwise specified	subgroups	type	Min	Max	
Error amplifier section - Co	ntinued						
Power supply rejection ratio	PSRR	V _{CC} = 12 V, 25 V	1, 2, 3	All	60		dB
Output sink current	I _{SINK}	V _{FB} = 2.7 V, V _{COMP} = 1.1 V	1, 2, 3	All	2		mA
Output source current	I _{SRC}	V _{FB} = 2.3 V, V _{COMP} = 5 V	1, 2, 3	All	-0.5		mA
Output voltage, high level	V _{OH}	$V_{FB} = 2.3 \text{ V},$ R _I = 15 k Ω TO GND	1, 2, 3	All	5.0		V
Output voltage, low level	V _{OL}	V_{FB} = 2.7 V, R _I = 15 k Ω TO V _{REF} pin	1, 2, 3	All		1.1	V
Current sense section							
Gain	A _V		4, 5, 6	All	2.85	3.15	V/V
Maximum current sense input threshold	V _{TH}	I _{SENSE} < 1.1 V	1, 2, 3	All	0.90	1.10	mA
Input bias current	I _{IB}		1, 2, 3	All		-10	μ A
Delay to output	t _{OUT}	T _A = +125°C	10	All		100	ns
Output section							
Output low level voltage	V _{OL}	I _{OUT} =20 mA	1, 2, 3	All		0.4	V
		I _{OUT} = 200 mA				2.2	

See footnotes at end of table.

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	T/	ABLE I. Electrical performance cha	<u>ıracteristics</u> - Co	ontinued.			
Test	Symbol	Conditions <u>1</u> / <u>2</u> /	Group A	Device	Lir	mits	Units
		-55° C ≤ T _A ≤ +125° C unless otherwise specified	subgroups	type	Min	Max	j
Output section - Continu	ned						
Output high level	V _{OH}	I _{OUT} = 20 mA	1, 2, 3	All	12.0		V
voltage		I _{OUT} = 200 mA			11.75		<u> </u>
Output voltage clamp	V _{OC}	I _{OUT} = 1 mA	1, 2, 3	All		19	V
Perfromance section							
Startup threshold	V _{THR}		1, 2, 3	01	9.0	10.2	V
voltage			!	02, 04	15	17]
				03, 05	7.8	9.0]
Minimum operating	V _{MIN}		1, 2, 3	01, 03, 05	7.0	8.2	V
voltage	l		!	02, 04	9.0	11]
Hysteresis	HYST	T _A = +25° C	1	01	1.6		V
				02, 04	5.5]
			<u> </u>	03, 05	0.4		ĺ
Maximum duty cycle		T _A = +25° C	4	01, 04, 05	46		%
				02, 03	94]
Startup current	I _{SU}		1, 2, 3	All		250	μΑ
Operating current	I _{CC}		1, 2, 3	All		10	mA

 $[\]underline{1}$ / Unless otherwise specified, V_{CC} = 15 V, timing resistance (R_T) = 10 k Ω , and timing capacitance (C_T) = 3.3 nF. See figure 3.

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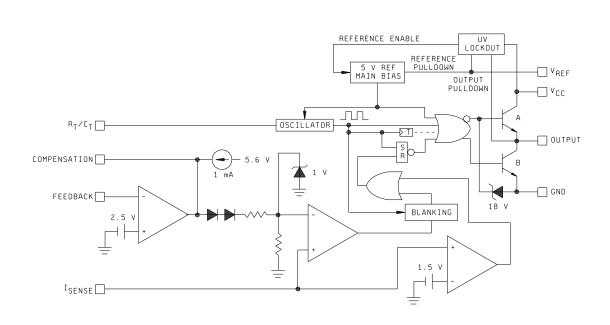
 $[\]underline{2}$ / Low duty cycle pulse techniques are used during test to maintain junction temperature close to ambient.

Device type	01
Case outline	Р
Terminal number	Terminal symbol
1 2 3 4 5 6 7	COMPENSATION (COMP) FEEDBACK (FB) CURRENT SENSE TIMING RESISTANCE (R_T)/TIMING CAPACITANCE (C_T) GROUND OUTPUT VOLTAGE (V_{OUT}) V_{CC} V_{RFF}

FIGURE 1. <u>Terminal connections</u>.

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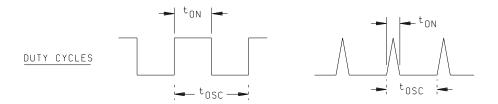


NOTE: Resistors shown in diagram are internal resistors to the die.

FIGURE 2. Logic diagram.

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Maximum duty cycle (%) =
$$\frac{t_{ON}}{t_{OSC}}$$
 x 100

Approximate minimum duty cycle (actual minimum duty cycle = 0%)

FIGURE 3. Timing waveforms.

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- 4.2 <u>Screening</u>. For device class M, screening shall be in accordance with method 5004 of MIL-STD-883, and shall be conducted on all devices prior to quality conformance inspection. For device classes Q and V, screening shall be in accordance with MIL-I-38535, and shall be conducted on all devices prior to qualification and technology conformance inspection.
 - 4.2.1 Additional criteria for device class M.
 - a. Burn-in test, method 1015 of MIL-STD-883.
 - (1) Test condition B. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1015.
 - (2) $T_A = +125^{\circ} C$, minimum.
 - b. Interim and final electrical test parameters shall be as specified in table II herein.
 - 4.2.2 Additional criteria for device classes Q and V.
 - a. The burn-in test duration, test condition and test temperature, or approved alternatives shall be as specified in the device manufacturer's QM plan in accordance with MIL-I-38535. The burn-in test circuit shall be maintained under document revision level control of the device manufacturer's Technology Review Board (TRB) in accordance with MIL-I-38535 and shall be made available to the acquiring or preparing activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1015.
 - b. Interim and final electrical test parameters shall be as specified in table II herein.
 - Additional screening for device class V beyond the requirements of device class Q shall be as specified in appendix B of MIL-I-38535.
- 4.3 Qualification inspection for device classes Q and V. Qualification inspection for device classes Q and V shall be in accordance with MIL-I-38535. Inspections to be performed shall be those specified in MIL-I-38535 and herein for groups A, B, C, D, and E inspections (see 4.4.1 through 4.4.4).
- 4.4 <u>Conformance inspection</u>. Quality conformance inspection for device class M shall be in accordance with MIL-STD-883 (see 3.1 herein) and as specified herein. Inspections to be performed for device class M shall be those specified in method 5005 of MIL-STD-883 and herein for groups A, B, C, D, and E inspections (see 4.4.1 through 4.4.4). Technology conformance inspection for classes Q and V shall be in accordance with MIL-I-38535 including groups A, B, C, D, and E inspections and as specified herein except where option 2 of MIL-I-38535 permits alternate in-line control testing.
 - 4.4.1 Group A inspection.
 - a. Tests shall be as specified in table II herein.
 - b. Subgroups 7, 8, 9, and 11 in table I, method 5005 of MIL-STD-883 shall be omitted.
 - 4.4.2 <u>Group C inspection</u>. The group C inspection end-point electrical parameters shall be as specified in table II herein.
 - 4.4.2.1 Additional criteria for device class M. Steady-state life test conditions, method 1005 of MIL-STD-883:
 - a. Test condition B. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1005.
 - b. $T_A = +125^{\circ}C$, minimum.
 - c. Test duration: 1,000 hours, except as permitted by method 1005 of MIL-STD-883.

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TABLE II. Electrical test requirements.

Test requirements	Subgroups (in accordance with MIL-STD-883, TM 5005, table I)	Subgroups (in accordance with MIL-I-38535, table III)	
	Device class M	Device class Q	Device class V
Interim electrical parameters (see 4.2)			
Final electrical parameters (see 4.2)	1, 2, 3, 4, 5, 6, 10 <u>1</u> /	1, 2, 3, 4, 5, 6, 10 <u>1</u> /	1, 2, 3, 4, 5, 6, 10 <u>1</u> /
Group A test requirements (see 4.4)	1, 2, 3, 4, 5, 6, 10	1, 2, 3, 4, 5, 6, 10	1, 2, 3, 4, 5, 6, 10
Group C end point electrical parameters (see 4.4)	1, 2, 3	1, 2, 3	1, 2, 3
Group D end point electrical parameters (see 4.4)	1, 2, 3	1, 2, 3	1, 2, 3
Group E end point electrical parameters (see 4.4)			

^{1/} PDA applies to subgroup 1.

- 4.4.2.2 <u>Additional criteria for device classes Q and V.</u> The steady-state life test duration, test condition and test temperature, or approved alternatives shall be as specified in the device manufacturer's QM plan in accordance with MIL-I-38535. The test circuit shall be maintained under document revision level control by the device manufacturer's TRB, in accordance with MIL-I-38535, and shall be made available to the acquiring or preparing activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1005.
 - 4.4.3 Group D inspection. The group D inspection end-point electrical parameters shall be as specified in table II herein.
- 4.4.4 <u>Group E inspection</u>. Group E inspection is required only for parts intended to be marked as radiation hardness assured (see 3.5 herein). RHA levels for device classes Q and V shall be M, D, R, and H and for device class M shall be M and D.
 - a. End-point electrical parameters shall be as specified in table II herein.
 - b. For device class M, the devices shall be subjected to radiation hardness assured tests as specified in MIL-I-38535, appendix A, for the RHA level being tested. For device classes Q and V, the devices or test vehicle shall be subjected to radiation hardness assured tests as specified in MIL-I-38535 for the RHA level being tested. All device classes must meet the postirradiation end-point electrical parameter limits as defined in table I at T_A = +25° C ±5° C, after exposure, to the subgroups specified in table II herein.
 - c. When specified in the purchase order or contract, a copy of the RHA delta limits shall be supplied.

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5. PACKAGING

5.1 <u>Packaging requirements</u>. The requirements for packaging shall be in accordance with MIL-STD-883 (see 3.1 herein) for device class M and MIL-I-38535 for device classes Q and V.

6. NOTES

- 6.1 <u>Intended use</u>. Microcircuits conforming to this drawing are intended for use for Government microcircuit applications (original equipment), design applications, and logistics purposes.
- 6.1.1 Replaceability. Microcircuits covered by this drawing will replace the same generic device covered by a contractor-prepared specification or drawing.
 - 6.1.2 Substitutability. Device class Q devices will replace device class M devices.
- 6.2 <u>Configuration control of SMD's</u>. All proposed changes to existing SMD's will be coordinated with the users of record for the individual documents. This coordination will be accomplished in accordance with MIL-STD-973 using DD Form 1692, Engineering Change Proposal.
- 6.3 Record of users. Military and industrial users shall inform Defense Electronics Supply Center when a system application requires configuration control and which SMD's are applicable to that system. DESC will maintain a record of users and this list will be used for coordination and distribution of changes to the drawings. Users of drawings covering microelectronic devices (FSC 5962) should contact DESC-EC, telephone (513) 296-6047.
- 6.4 <u>Comments</u>. Comments on this drawing should be directed to DESC-EC, Dayton, Ohio 45444-5270, or telephone (513) 296-5377.
- 6.5 <u>Abbreviations, symbols, and definitions</u>. The abbreviations, symbols, and definitions used herein are defined in MIL-I-38535 and MIL-STD-1331.
- 6.6 One part one part number system. The one part one part number system described below has been developed to allow for transitions between identical generic devices covered by the three major microcircuit requirements documents (MIL-H-38534, MIL-I-38535, and 1.2.1 of MIL-STD-883) without the necessity for the generation of unique PIN's. The three military requirements documents represent different class levels, and previously when a device manufacturer upgraded military product from one class level to another, the benefits of the upgraded product were unavailable to the Original Equipment Manufacturer (OEM), that was contractually locked into the original unique PIN. By establishing a one part number system covering all three documents, the OEM can acquire to the highest class level available for a given generic device to meet system needs without modifying the original contract parts selection criteria.

Military documentation format	Example PIN under new system	Manufacturing source listing	Document <u>listing</u>
New MIL-H-38534 Standardized Military Drawings	5962-XXXXXZZ(H or K)YY	QML-38534	MIL-BUL-103
New MIL-I-38535 Standardized Military Drawings	5962-XXXXXZZ(Q or V)YY	QML-38535	MIL-BUL-103
New 1.2.1 of MIL-STD-883 Standardized Military Drawings	5962-XXXXXZZ(M)YY	MIL-BUL-103	MIL-BUL-103

6.7 Sources of supply.

- 6.7.1 <u>Sources of supply for device classes Q and V</u>. Sources of supply for device classes Q and V are listed in QML-38535. The vendors listed in QML-38535 have submitted a certificate of compliance (see 3.6 herein) to DESC-EC and have agreed to this drawing.
- 6.7.2 <u>Approved sources of supply for device class M</u>. Approved sources of supply for class M are listed in MIL-BUL-103. The vendors listed in MIL-BUL-103 have agreed to this drawing and a certificate of compliance (see 3.6 herein) has been submitted to and accepted by DESC-EC.

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STANDARDIZED MILITARY DRAWING SOURCE APPROVAL BULLETIN

DATE: 93-10-28

Approved sources of supply for SMD 5962-93190 are listed below for immediate acquisition only and shall be added to MIL-BUL-103 during the next revision. MIL-BUL-103 will be revised to include the addition or deletion of sources. The vendors listed below have agreed to this drawing and a certificate of compliance has been submitted to and accepted by DESC-EC. This bulletin is superseded by the next dated revision of MIL-BUL-103.

Standardized military drawing PIN	Vendor CAGE number	Vendor similar PIN <u>1</u> /
5962-9319001MPX	64155	LT1241MJ8/883C
5962-9319002MPX	64155	LT1242MJ8/883C
5962-9319003MPX	64155	LT1243MJ8/883C
5962-9319004MPX	64155	LT1244MJ8/883C
5962-9319005MPX	64155	LT1245MJ8/883C

<u>1</u>/ <u>Caution</u>. Do not use this number for item acquisition. Items acquired to this number may not satisfy the performance requirements of this drawing.

Vendor CAGEVendor namenumberand address

64155 Linear Technology Corporation

1630 McCarthy Boulevard Milpitas, CA 95035-7487

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